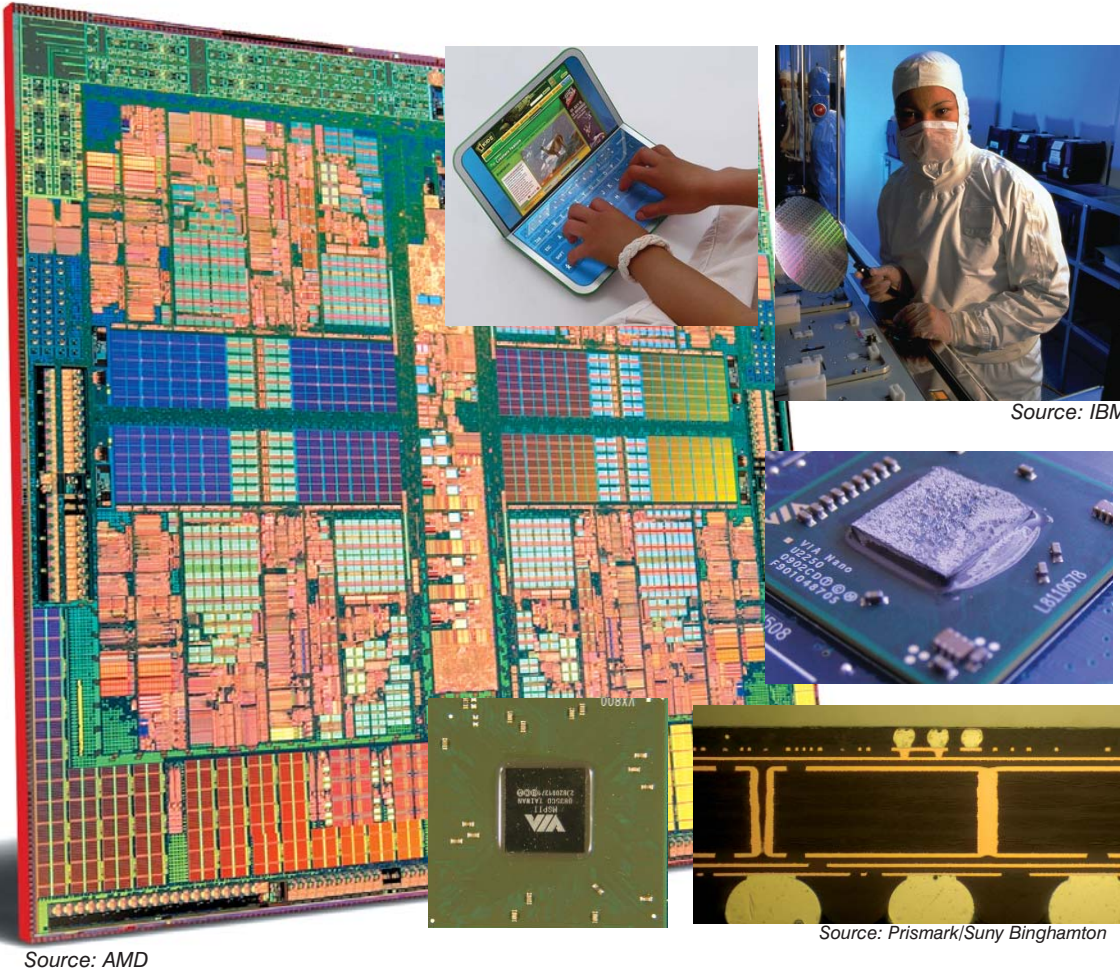


THE SEMICONDUCTOR AND PACKAGING REPORT

FOURTH QUARTER • MARCH 2010



Prismark's Semiconductor and Packaging Report is published quarterly and provides semiconductor manufacturers, semiconductor packaging companies and their materials, process, and equipment suppliers with a comprehensive review and analysis of changes in the global semiconductor packaging industry and how these changes will affect their business.

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*CONSULTANTS TO THE ELECTRONICS INDUSTRY
BUSINESS OPPORTUNITY FROM TECHNOLOGY AND
MARKET CHANGES*

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